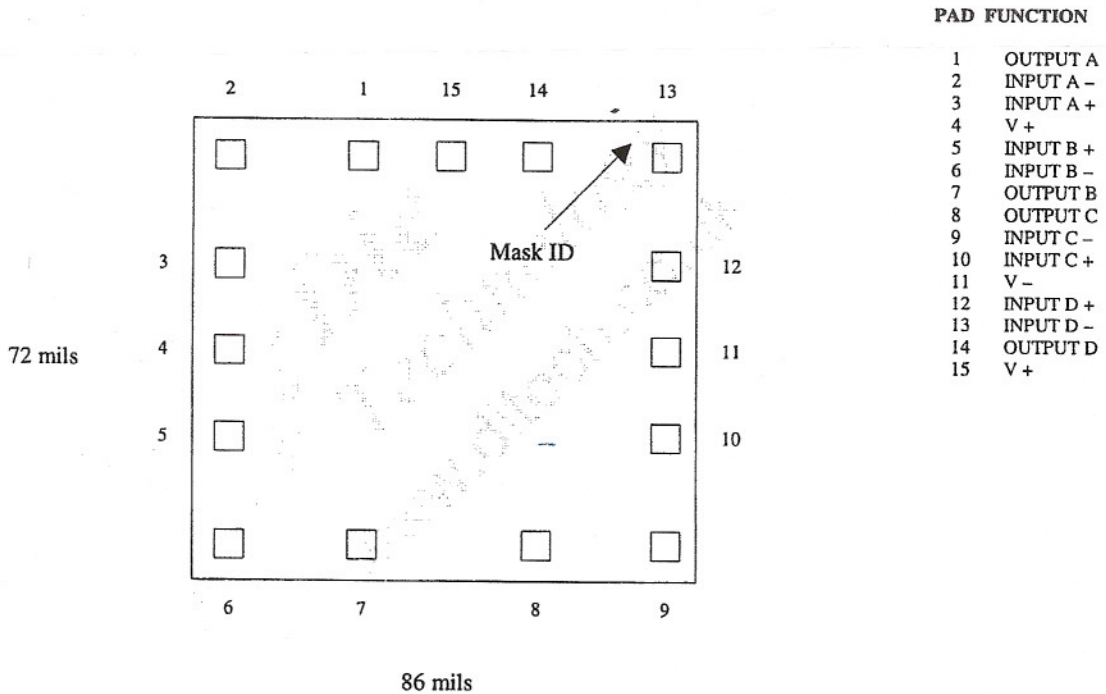




# Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



### PAD FUNCTION

- 1 OUTPUT A
- 2 INPUT A -
- 3 INPUT A +
- 4 V +
- 5 INPUT B +
- 6 INPUT B -
- 7 OUTPUT B
- 8 OUTPUT C
- 9 INPUT C -
- 10 INPUT C +
- 11 V -
- 12 INPUT D +
- 13 INPUT D -
- 14 OUTPUT D
- 15 V +

NOTE: Both V+ pads are common. Either or both may be connected.

**Topside Metal: Aluminum**  
**Backside Metal: Silicon**  
**Backside Potential: Floating**  
**Bond Pad Size: .004" min.**  
**Mask Ref:**

APPROVED BY: C Dawson

DIE SIZE : .072" X .086 "

DATE: 3/22/10

MFG: Analog

THICKNESS: .020"

Part # OP11NBC